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polyEpoxy resin compsn. for sealing semiconductor - including e.g. reaction prod. of organopolysiloxane with terminal epoxy cpds. and aminosilane

Patent Assignee: TORAY IND INC (TORA)
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Patent Family:

Patent No	Kind	Date	Applicat No	Kind	Date	Week	
JP 2151622	A	19900611	JP 88307103	A	19881205	199029	B
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Patent Details:

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JP 2591124	B2		6	C08L-063/00	Previous Publ. patent JP 2151622

Abstract (Basic): JP 2151622 A

Epoxy resin compsn. comprises (A) epoxy resin. (B) a curing agent, (C) modified organopolysiloxane, i.e., reaction product of (C1) organopolysiloxane having epoxy gps. at both terminals with aminosilane and/or reaction prodt of (C2) organopolysiloxane contg. polyalkyleneoxide at the side chain with aminosilane, and (D) silica .

Specially The chemical equivalent ratio of resin (A) to component (B) is 1:0.5.5-1.5, pref. 1:0.7-1.3. The content of (B) is 1-20 1-20, pref. 2-15 wt % in the compsn. The content of (D) is 65-85 wt % in the epoxy resin compsn. The equivalent ratio of aminosilane to (C1) or C2) is 1:0.9-02, pref., 1:0.7-0.5. The compsn. opt. contains a curing promoter, a releasing agent, a coupling agent, a flame-retarder a colouring agent, etc.

USE/ADVANTAGE - The epoxy resin compsn, has low bending modulas of elasticity and good low stress and hardly causes cracking and burr.. The compsn. has good printing properties. The semiconductor sealed with the resin compsn has improved reliability

Title Terms: POLYEPOXIDE; RESIN; COMPOSITION; SEAL; SEMICONDUCTOR; REACT; PRODUCT; ORGANO; POLYSILOXANE; TERMINAL; EPOXY; COMPOUND; AMINO; SILANE
Derwent Class: A21; A85; L03; U11
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International Patent Class (Additional): C08G-059/17; C08G-059/18; C08K-003/36; C08L-083/04; H01L-023/29; H01L-023/31; C08L-063/00; C08L-083-04
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